# 1. General description

Trench Schottky barrier rectifier encapsulated in a CFP2-HP (SOD323HP) power flat lead Surface-Mounted Device (SMD) plastic package.

### 2. Features and benefits

- · Low forward voltage
- Low Q<sub>rr</sub> and low I<sub>RM</sub>
- · Low leakage current
- High power capability due to clip-bonding technology
- Power flat lead plastic package with exposed heatsink for optimal thermal connection
- · Qualified according to AEC-Q101 and recommended for use in automotive applications

### 3. Applications

- · High efficiency DC-to-DC conversion
- · Automotive LED lighting
- · Switch mode power supply
- Freewheeling applications
- · Reverse polarity protection
- OR-ing

### 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5; f = 20 kHz; square wave; T <sub>sp</sub> $\leq$ 167 °C		-	-	2	Α
$V_R$	reverse voltage	T <sub>j</sub> = 25 °C		-	-	100	V
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 2 A; pulsed; T <sub>j</sub> = 25 °C	[1]	-	810	880	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 100 V; pulsed; T <sub>j</sub> = 25 °C	[1]	-	0.12	0.6	μΑ
		V <sub>R</sub> = 100 V; pulsed; T <sub>j</sub> = 125 °C	[1]	-	0.18	0.75	mA

<sup>[1]</sup> Very short pulse, in order to maintain a stable junction temperature.



# 5. Pinning information

#### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode	Transparent top view  CFP2-HP (SOD323HP)	K A sym001

# 6. Ordering information

#### **Table 3. Ordering information**

Type number	Package							
	Name	Description	Version					
PMEG100T20ELXD-Q	CFP2-HP	SOD323HP: plastic surface-mounted package with solderable lead ends; 2.2 mm x 1.3 mm x 0.68 mm body	SOD323HP					

# 7. Marking

#### Table 4. Marking codes

Type number	Marking code
PMEG100T20ELXD-Q	2P

# 8. Limiting values

### **Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_R$	reverse voltage	T <sub>j</sub> = 25 °C		-	100	V
l <sub>F</sub>	forward current	$\delta$ = 1; $T_{sp} \le 165 ^{\circ}\text{C}$		-	2.8	Α
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5; f = 20 kHz; square wave; T <sub>sp</sub> ≤ 167 °C		-	2	А
I <sub>FSM</sub>	non-repetitive peak forward current	$t_p$ = 8.3 ms; half sine wave; $T_{j(init)}$ = 25 °C		-	33	А
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	[1]	-	0.65	W
			[2]	-	1.2	W
Tj	junction temperature			-	175	°C
T <sub>amb</sub>	ambient temperature			-55	175	°C
T <sub>stg</sub>	storage temperature			-65	175	°C

<sup>[1]</sup> Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

## 9. Thermal characteristics

**Table 6. Thermal characteristics** 

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
R <sub>th(j-a)</sub>	thermal resistance from	in free air	[1] [2]	-	-	230	K/W
junction to	junction to ambient	ient	[1] [3]	-	-	125	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[4]	-	-	6	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P<sub>R</sub> are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [4] Soldering point of cathode tab.

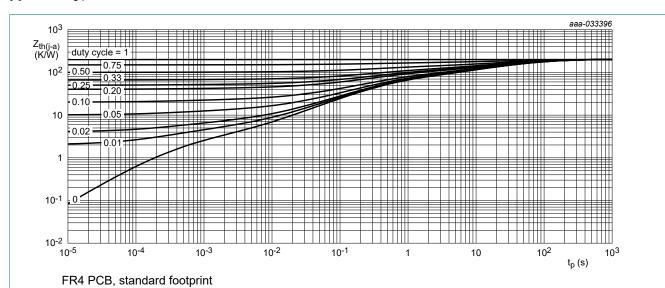


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

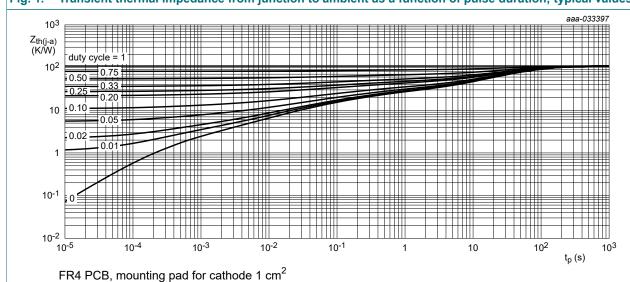


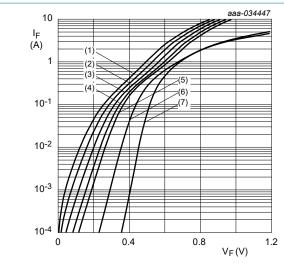
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

# 10. Characteristics

**Table 7. Characteristics** 

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
$V_{(BR)R}$	reverse breakdown voltage	$I_R = 1 \text{ mA}$ ; pulsed; $T_j = 25 \text{ °C}$	[1]	100	-	-	V
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 0.5 A; pulsed; T <sub>j</sub> = 25 °C	[1]	-	570	650	mV
		I <sub>F</sub> = 1 A; pulsed; T <sub>j</sub> = 25 °C	[1]	-	680	760	mV
		I <sub>F</sub> = 2 A; pulsed; T <sub>j</sub> = 25 °C	[1]	-	810	880	mV
		I <sub>F</sub> = 2 A; pulsed; T <sub>j</sub> = -40 °C	[1]	-	820	890	mV
		I <sub>F</sub> = 2 A; pulsed; T <sub>j</sub> = 125 °C	[1]	-	640	720	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 100 V; pulsed; T <sub>j</sub> = 25 °C	[1]	-	0.12	0.6	μΑ
		V <sub>R</sub> = 100 V; pulsed; T <sub>j</sub> = 125 °C	[1]	-	0.18	0.75	mA
		V <sub>R</sub> = 100 V; pulsed; T <sub>j</sub> = 150 °C	[1]	-	0.75	4	mA
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 1 V; f = 1 MHz; T <sub>j</sub> = 25 °C		-	120	-	pF
		V <sub>R</sub> = 10 V; f = 1 MHz; T <sub>j</sub> = 25 °C		-	35	-	pF
t <sub>rr</sub>	reverse recovery time step recovery	$I_F = 0.5 \text{ A}$ ; $I_R = 1 \text{ A}$ ; $I_{R(meas)} = 0.25 \text{ A}$ ; $I_j = 25 \text{ °C}$		-	3	-	ns
	reverse recovery time ramp recovery	$dI_F/dt = 100 \text{ A/}\mu\text{s}; I_F = 1 \text{ A}; V_R = 30 \text{ V};$ $T_j = 25 ^{\circ}\text{C}$		-	6	-	ns
I <sub>RM</sub>	peak reverse recovery current			-	0.285	-	Α
Q <sub>rr</sub>	reverse recovery charge			-	1.2	-	nC
$V_{FRM}$	peak forward recovery voltage	$I_F = 0.5 \text{ A}; \text{ d}I_F/\text{d}t = 20 \text{ A/µs}; T_j = 25 ^{\circ}\text{C}$		-	570	-	mV

<sup>[1]</sup> Very short pulse, in order to maintain a stable junction temperature.



pulsed condition

(1) Tj = 175 °C

(2) Tj = 150 °C

(3) Tj = 125 °C

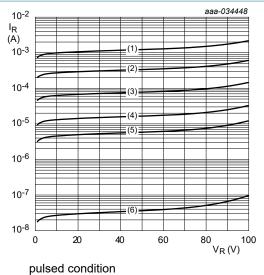
(4) Tj = 100 °C

(5) Tj = 85 °C

(6) Tj = 25 °C

(7) Tj = -40 °C

Forward current as a function of forward Fig. 3. voltage; typical values



(1)  $T_j = 175 \, ^{\circ}C$ 

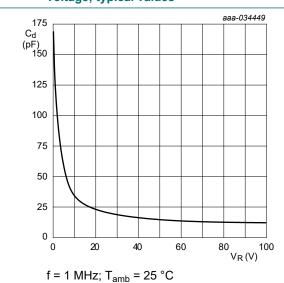
(2)  $T_j = 150 \, ^{\circ}\text{C}$ 

(3)  $T_j^J = 125 °C$  (4)  $T_j = 100 °C$ 

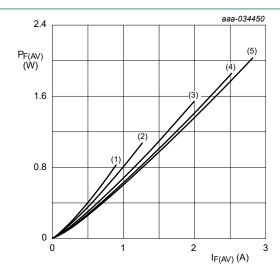
(5)  $T_i = 85 °C$ 

(6)  $T_{j}^{'} = 25 \, ^{\circ}\text{C}$ 

Fig. 4. Reverse current as a function of reverse voltage; typical values



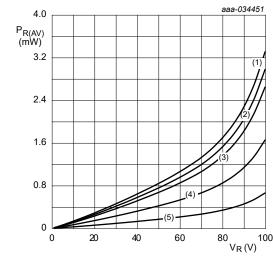
Diode capacitance as a function of reverse Fig. 5. voltage; typical values



T<sub>i</sub> = 100 °C  $(1) \delta = 0.1$  $(2) \delta = 0.2$  $(3) \delta = 0.5$ 

 $(4) \delta = 0.8$ (5)  $\delta$  = 1; DC

Fig. 6. Average forward power dissipation as a function of average forward current; typical values



T<sub>i</sub> = 100 °C

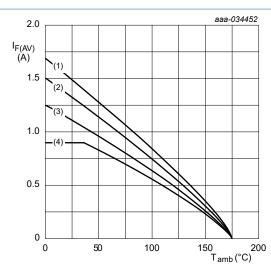
 $(1) \delta = 1; DC$ 

 $(2) \delta = 0.9$ 

 $(3) \delta = 0.8$  $(4) \delta = 0.5$ 

 $(5) \delta = 0.2$ 

Average reverse power dissipation as a Fig. 7. function of reverse voltage; typical values



FR4 PCB, standard footprint

 $T_i = 175 \,{}^{\circ}\text{C}$ 

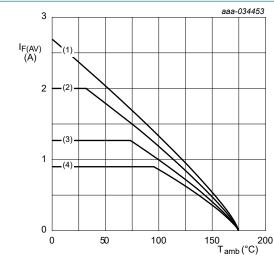
 $(1) \delta = 1$ ; DC

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

 $(4) \delta = 0.1$ ; f = 20 kHz

Fig. 8. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>  $T_i = 175 \,{}^{\circ}\text{C}$ 

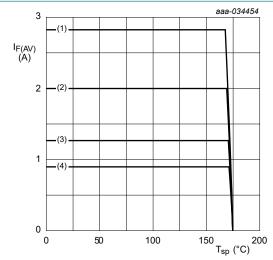
 $(1) \delta = 1$ ; DC

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



Tj = 175 °C

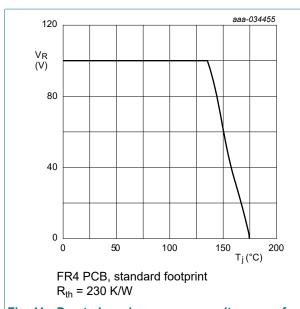
(1)  $\delta$  = 1; DC

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 10. Average forward current as a function of solder point temperature; typical values

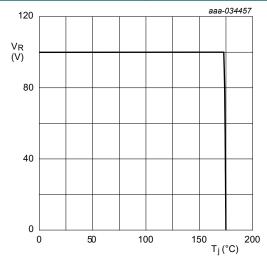


aaa-034456 120 V<sub>R</sub> (V) 80 40 0 50 100 150 FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

 $R_{th}$  = 125 K/W

of junction temperature; typical values

Fig. 11. Derated maximum reverse voltage as a function | Fig. 12. Derated maximum reverse voltage as a function of junction temperature; typical values



Soldering point of cathode tab  $R_{th} = 6 \text{ K/W}$ 

Fig. 13. Derated maximum reverse voltage as a function of junction temperature; typical values

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# 11. Test information

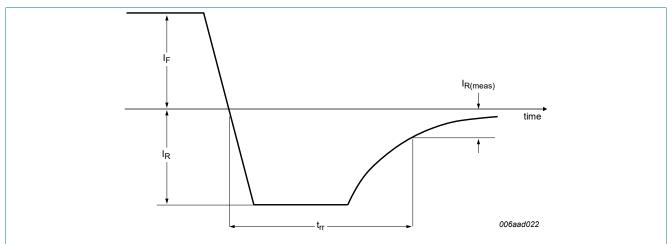


Fig. 14. Reverse recovery definition; step recovery

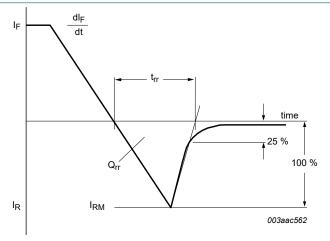


Fig. 15. Reverse recovery definition; ramp recovery

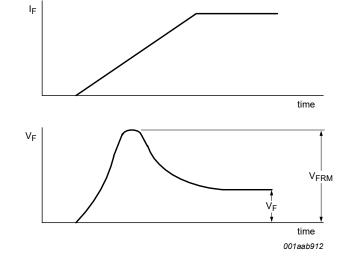
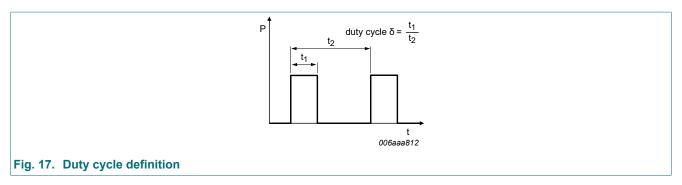


Fig. 16. Forward recovery definition



The current ratings for the typical waveforms are calculated according to the equations:

 $I_{F(AV)}=I_M\times\delta$  with  $I_M$  defined as peak current

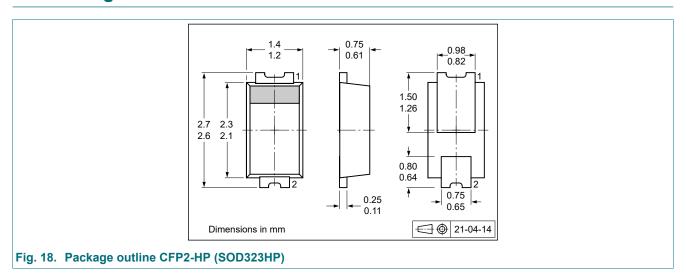
 $I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_M \times \sqrt{\delta}$ 

with  $I_{\text{RMS}}$  defined as RMS current.

### **Quality information**

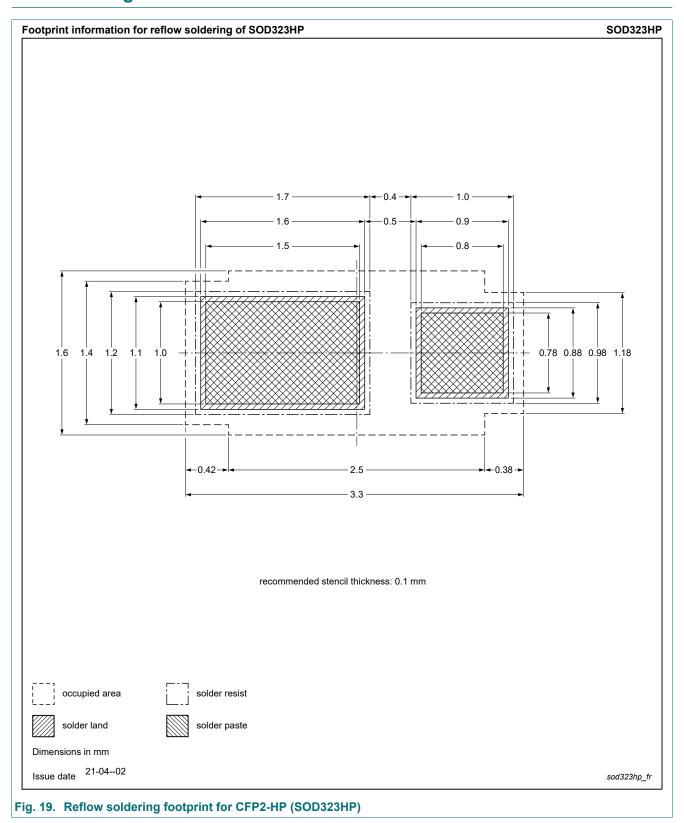
This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

# 12. Package outline



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# 13. Soldering



# 14. Revision history

#### **Table 8. Revision history**

Data sheet ID	Release date		Change notice	Supersedes
PMEG100T20ELXD-Q v.1	20220401	Product data sheet	-	-

### 15. Legal information

#### **Data sheet status**

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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